

IN THE CLAIMS

Please cancel Claims 2 - 25 and 27 - 28.

Please amend Claims 26 and 29 as follows:

✓ ✓
P 26. (amended) A method of polishing a target member,
comprising polishing a target member by use of the abrasive of
Claim 1.

✓ ✓
P 29. (amended) A process for producing a semiconductor device,
comprising the step of polishing a semiconductor chip on which
a silica film has been formed, by use of the abrasive of Claim
1.